

ABSTRACT OF THE DISCLOSURE

MOLD FOR FLASHLESS INJECTION MOLDING
TO ENCAPSULATE AN INTEGRATED CIRCUIT CHIP

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An injection mold is provided for injection molding an encapsulation material to encapsulate at least one integrated circuit chip. The injection mold includes at least two parts that define at least one injection circuit, and at least one blind complementary channel communicating with the injection circuit. The injection circuit includes at least one injection cavity for housing the chip, at least one transfer chamber from which the encapsulation material is injected, and at least one injection channel connecting the transfer chamber to the injection cavity. The blind complementary channel is formed between the two parts of the mold and forms at least one appendage of encapsulation material that is connected to the encapsulation material that fills the injection circuit. Also provided is a method for injection molding an encapsulation material to encapsulate at least one integrated circuit chip.

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